SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

- 3-State Outputs Drive Bus Lines Directly
- Encodes 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:

 N-Bit Encoding
 Code Converters and Generators
- Typical Data Delay . . . 15 ns
- Typical Power Dissipation . . . 60 mW

description

These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The 'LS348 circuits encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input E1 and enable output E0) has been provided to allow octal expansion. Outputs A0, A1, and A2 are implemented in three-state logic for easy expansion up to 64 lines without the need for external circuitry. See Typical Application Data.

FUNCTION TABLE

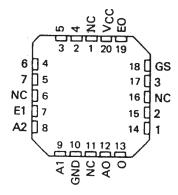
INPUTS									Ol	JTPU	TS		
EI	0	1	2	3	4	5	6	7	A2	A1	A0	GS	EO
Н	Х	Х	Χ	Х	Χ	X	X	Χ	Z	Z	Z	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	z	Z	Z	н	L
L	Х	Χ	Х	Х	Х	Χ	Х	L	L	L	L	L	н
L	Х	Х	Χ	Х	Х	Х	L	Н	L	L	Н	L	н
L	Х	Х	Χ	X	Х	L	Н	Н	L	Н	L	L	н
L	Х	Х	Χ	Х	L	Н	Н	Н	L	Н	Н	L	н
L	Ý	Х	Х	L	Н	Н	Н	Н	н	L	L	L	н
L	Х	Х	L	Н	Н	Н	Н	Н	н	L	Н	L	н
L	X	L	Н	H	Н	Н	Н	Н	н	Н	L	L	н
L	L	Н	Н	Н	H	Н	Н	Н	Н	Н	Н	L	н

H = high logic level, L = low logic level, X = irrelevant

SN54LS348 . . . J OR W PACKAGE SN74LS348 . . . D OR N PACKAGE (TOP VIEW)

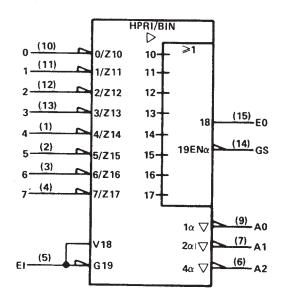
4 🛮 1	U ₁₆	Vcc
5 🛮 2	15] EO
6 □3	14	GS
7 🛮 4	13]3
E1 ∏5	12] 2
A2 🗍 6	11] 1
A1 □7	10] 0
GND [8	9	OA [

SN54LS348 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol[†]



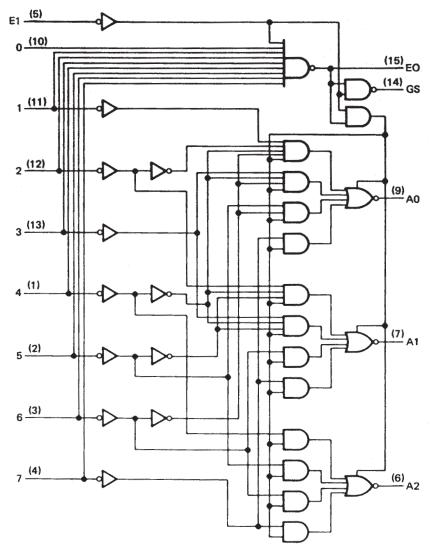
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



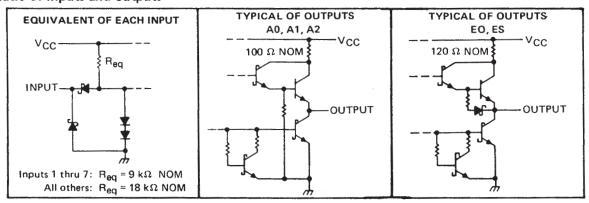
Z = high-impedance state

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematic of inputs and outputs





SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		٧
Input voltage		٧
Operating free-air temperature range:	SN54LS348	°C
	N74LS348	°C
Storage temperature range		°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	·	SN54LS348			SN74LS348			
		MIN NOM MAX				NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5,25	V
High-level output current, IOH	A0, A1, A2			-1			-2.6	mA
migriever output current, 10H	EO, GS			-400			-400	μА
Low-level output current, IOI	A0, A1, A2			12			24	mA
- Converse of the Content to C	EO, GS			4			8	mA
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CO	SN54LS348			SN74LS348				
			TEST CONDITIONS†			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			2			V	
VIL	Low-level input voltage					**	0.7			0.8	V
ViK	Input clamp voltage		V _{CC} = MIN,	I ₁ = -18 mA			-1.5			-1.5	V
	High-level	A0, A1, A2	V _{CC} = MIN,	I _{OH} = -1 mA	2.4	3.1					
v_{OH}	output voltage	A0, A1, A2	V _{!H} = 2 V,	I _{OH} = -2.6 mA				2.4	3,1		V
		EO, GS	VIL = VILmax	$I_{OH} = -400 \mu A$	2.5	3.4		2.7	3.4		1
		A0, A1, A2	V _{CC} = MIN,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL	Low-level	A0, A1, A2	V _{IH} = 2 V,	OL = 24 mA					0,35	0.5	v
*OL	Output voltage	EO, GS	1	¹ OL = 4 mA		0.25	0.4		0.25	0.4	
			VIL = VILmax	I _{OL} = 8 mA					0.35	0.5	
loz	Off-State (high-impedance	A0, A1, A2	V _{CC} = MAX,	V _O = 2.7 V			20		******	20	
.02	state) output current	A0, A1, A2	V _{IH} = 2 V	V _O = 0.4 V			-20			-20	μΑ
l ₁	Input current at maximum	Inputs 1 thru 7	V _{CC} = MAX,	V 7.V			0.2			0,2	
'1	input voltage	All other inputs	VCC = MAX,	V = / V			0.1			0.1	mA
Ιн	High-level input current	Inputs 1 thru 7	V MAAY	V - 22V			40			40	
'1H	riigitiever input current	All other inputs	V _{CC} = MAX,	V = 2.7 V			20			20	μΑ
HL	Low-level input current	Inputs 1 thru 7	V 144.V				-0.8			-0.8	
'1L	Low-level hiput current	All other inputs	V _{CC} = MAX,	V = 0.4 V			-0.4			-0.4	mA
I _{OS} S	Short-circuit output current §	Outputs A0, A1, A2	.,		-30		-130	-30		-130	<u> </u>
	onorconcuit output currents	Outputs EO, GS	V _{CC} = MAX		-20		-100	-20		-100	mA
lcc	Supply current		V _{CC} = MAX,	Condition 1		13	25		13	25	
.00	ouppry current	See Note 2	Condition 2		12	23		12	23	mA	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC (condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open. ICC (condition 2) is measured with all inputs and outputs open.



^{\$} All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$.

[§] Not more than one output should be shorted at a time.

SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

PARAMETER [†]	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
ФLН	1 thru 7	A0, A1, or A2	In-phase		111	11	17	ns	
tPHL.	1 11114 /	A0, A1, 01 A2	output	C. = 45 = 5		20	30	113	
ФLН	1 thru 7	A0, A1, or A2	Out-of-phase	CL = 45 pF,		23	35	35	
tPHL	i thru /	AU, A1, 01 A2	output	RL = 667 Ω, See Note 3		23	35	ns	
ФZH	EI	A0, A1, or A2		See Note 3		25	39	- ns l	
ΨZL] '	70, 71, 01 72				24	41		
tPLH	0 thru 7	EO	Out-of-phase			11	18 ns		
tPHL	O and /	20	output			26	40		
tPLH	O thru 7	0 thru 7 GS In-phase Output $C_L = 15 \text{ pF}$ FL = $2 \text{ k}\Omega$, See Note 3			38	55	ns		
tPHL	O and /			_		9	21	1 ""	
tPLH	EI				11	17			
tPHL	1 -	43	output	See Note S		14	36	ns	
ФLН	EI	EO	In-phase			17	26		
tPHL	1 "		output	:		25	40	ns	
tPHZ	EI	A0, A1, or A2		CL = 5 pF		18	27		
ヤLZ] -'	70, 71, 01 72		R _L = 667 Ω		23	35	ns	

[†] tpLH = propagation delay time, low-to-high-level output

tpzH = output enable time to high level

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

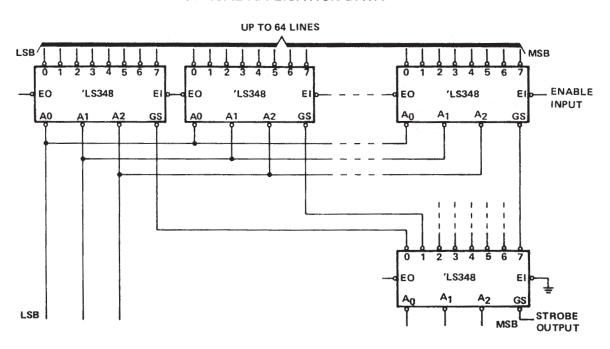


FIGURE 1-PRIORITY ENCODER WITH UP TO 64 INPUTS.



tpHL = propagation delay time, high-to-low-level output





.com 12-Jan-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/36002B2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
JM38510/36002BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS348D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS348NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS348FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS348W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI



PACKAGE OPTION ADDENDUM

www.ti.com	12-Jan-2006
to Customer on an annual basis.	

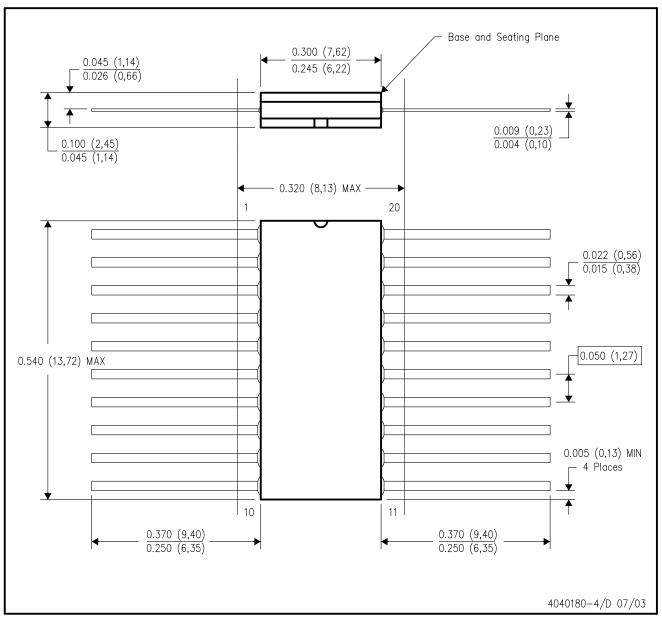
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



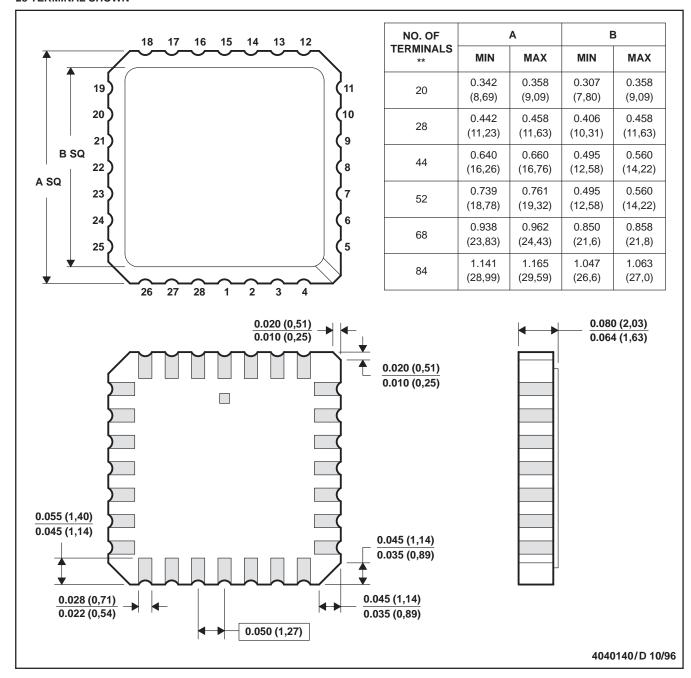
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

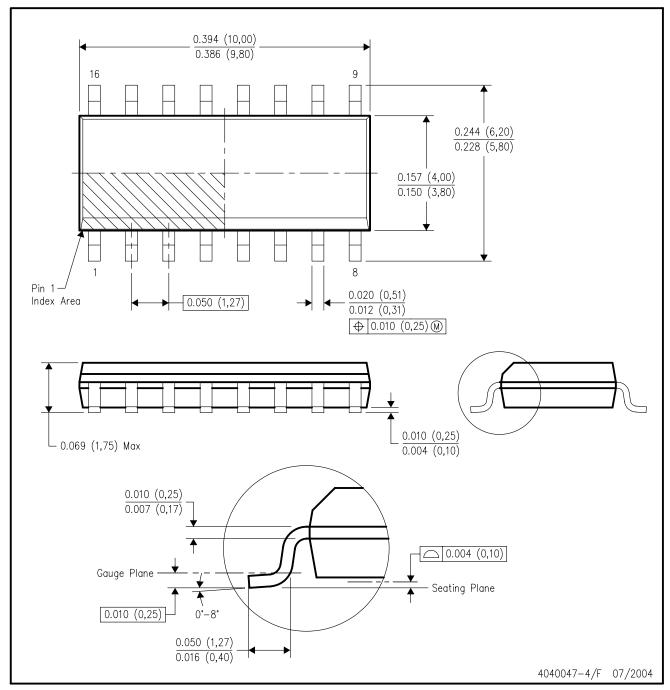


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated